

BZX84C0V3 THRU BZX84C33

330mW ZENER DIODE
3.3 VOLTS THRU 33 VOLTS
5% TOLERANCE



SOT-23 CASE

ABSOLUTE MAXIMUM RATINGS
Power Dissipation (at $T_A = 25^{\circ}\text{C}$)
Operating and Storage Temperature
Thermal Resistance

SYMBOLS
 P_D
 T_J, T_{stg}
 $R_{\theta JA}$

330
-55 to +125
257

UNIT
mW
 $^{\circ}\text{C}$
 $^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}\text{C}$, $I_Z = 5.0\text{mA}$ UNLESS OTHERWISE SPECIFIED)

Part	Zener Voltage V_Z (V)	Test Current I_Z (mA)	Maximum Zener Impedance		Minimum Zener Current		Maximum Zener Current	Maximum Operating Temperature Coefficient	Working Case
			Z_{0V} (V)	Z_{0V} (V)	I_{ZK} (V)	I_{ZK} (V)			
			500 mV	500 mV	500 mV	500 mV			
BZX84C0V3	3.3	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C0V4	3.6	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C0V5	3.9	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C0V6	4.2	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C0V7	4.5	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C0V8	4.8	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C0V9	5.1	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V0	5.4	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V1	5.7	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V2	6.0	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V3	6.3	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V4	6.6	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V5	6.9	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V6	7.2	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V7	7.5	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V8	7.8	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C1V9	8.1	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V0	8.4	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V1	8.7	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V2	9.0	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V3	9.3	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V4	9.6	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V5	9.9	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V6	10.2	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V7	10.5	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V8	10.8	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C2V9	11.1	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V0	11.4	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V1	11.7	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V2	12.0	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V3	12.3	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V4	12.6	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V5	12.9	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V6	13.2	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V7	13.5	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V8	13.8	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C3V9	14.1	5.0	10	10	0.5	0.5	35	±1%	35
BZX84C4V0	14.4	5.0	10	10	0.5	0.5	35	±1%	35

Central
Semiconductor Corp.

DESCRIPTION

The CENTRAL SEMICONDUCTOR BZX84C0V3 Series Silicon Zener Diode is a high quality voltage regulator for use in industrial, commercial, entertainment and computer applications.

Properties Of a Semi Conductor

Variable electrical conductivity

Semiconductors in their natural state are poor conductors because a *covalent* structure requires the flow of electrons, and semiconductors have their valence bands filled, preventing the entire flow of new electrons. Special doped techniques allow semiconducting materials to behave like conducting materials, such as *doping* or *gating*. These modifications have two categories: *n-type* and *p-type*. These refer to the excess or shortage of electrons, respectively. A balanced number of electrons would cause a current to flow throughout the material.[1]

Heterojunctions

Heterojunctions occur when two differently doped semiconducting materials are joined. For example, a configuration could consist of *p-doped* and *n-doped* germanium. This results in an exchange of electrons and holes between the differently doped semiconducting materials. The *n-doped* germanium would have an excess of electrons, and the *p-doped* germanium would have an excess of holes. The transfer occurs until an equilibrium is reached by a process called *diffusion*, which causes the migrating electrons from the *n-type* to come in contact with the migrating holes from the *p-type*. The result of this process is a narrow strip of immobile ions, which causes an electric field across the junction.[1][2]

Excited electrons

A difference in electric potential on a semiconducting material would cause it to leave thermal equilibrium and create a non-equilibrium situation. This involves electrons and holes at the system, which occurs via a process called *photoconductive effect*. Whenever thermal equilibrium is disturbed on a semiconducting material, the number of holes and electrons changes. Such disruptions can occur as a result of a temperature difference or *gating*, which can raise the system and create electrons and holes. The process that creates and stabilizes electrons and holes are called *generation* and *recombination*, respectively.[1]

Light emission

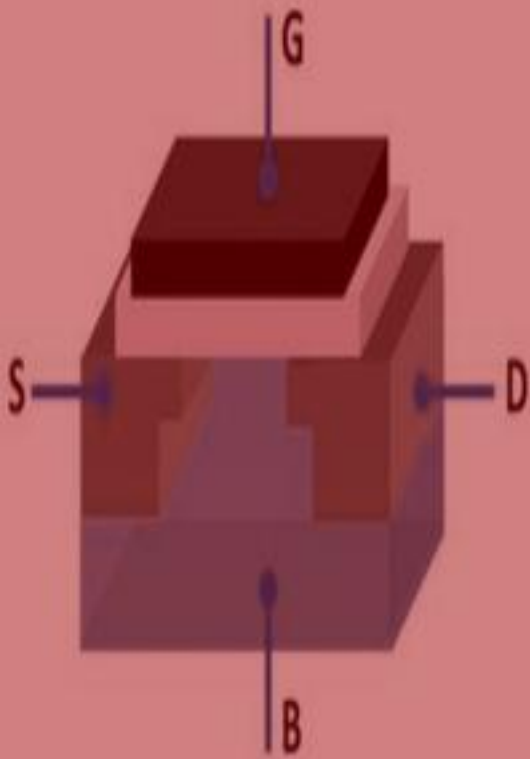
In certain semiconductors, excited electrons can return by emitting light instead of producing heat. [2] These semiconductors are used in the construction of *light emitting diodes* and *transistors* (quantum dots).

High thermal conductivity

Semiconductors with high thermal conductivity can be used for heat dissipation and improving thermal management of electronics.

Thermal energy conversion

Semiconductors have large **thermoelectric** power factors making them useful in **thermoelectric** generators, as well as high **thermoelectric** figures of merit making them useful in **thermoelectric** cooling.[3]



What is a Semiconductor?

A **semiconductor** material has an electrical conductivity value falling between that of a conductor, such as metallic copper, and an insulator, such as glass. Its conductivity falls in its intermediate class, usually between the square root, its **conducting** properties may be altered in useful ways by introducing impurities ("doping") into its crystal structure. When two differently doped regions join in the same crystal, a semiconductor junction is created. The behavior of charge carriers, which include electrons, ions, and electron holes, at these junctions is the basis of diodes, transistors, and many modern electronic devices. Some examples of semiconductors are silicon, germanium, gallium arsenide, and elements near the so-called "metalloid staircase" on the periodic table. When silicon, gallium arsenide is the second-most common semiconductor and is used in most diodes, solar cells, microwave-frequency integrated circuits, and others. Silicon is a critical element for fabricating most electronic circuits.

Semiconductor devices can display a range of useful properties, such as allowing current to flow more easily in one direction than the other, allowing variable resistance, and having sensitivity to light or heat. Because the electrical properties of a semiconductor material can be modified by doping, and by the application of electrical fields or light, devices made from semiconductors can be used for amplification, switching, and energy conversion.

The conductivity of silicon is increased by adding a small amount (of the order of 1 in 10⁹) of pentavalent elements, phosphorus, or arsenic, or trivalent elements boron, gallium, indium or zinc. This process is known as doping, and the resulting semiconductors are known as doped or extrinsic semiconductors. Apart from doping, the conductivity of a semiconductor can be improved by increasing its temperature. This is contrary to the behavior of a metal, in which conductivity decreases with an increase in temperature.

The modern understanding of the properties of a semiconductor relies on quantum physics to explain the movement of charge carriers in a crystal lattice.^[1] Doping greatly increases the number of charge carriers within the crystal. When a doped semiconductor contains free holes, it is called "p-type", and when it contains free electrons, it is known as "n-type". The semiconductor elements used in electronic devices are doped under precise conditions to control the concentrations and regions of p- and n-type regions. A single semiconductor device crystal can have many p- and n-type regions; the p-n junctions between these regions are responsible for the useful electronic behavior. Using a laser-point probe, one can determine quickly whether a semiconductor sample is p or n-type.^[2]

Some of the properties of semiconductor materials were observed throughout the mid 19th and first decades of the 20th century. The first practical application of semiconductors in electronics, was the 1964 development of the radio-shield detector, a p-n junction diode used in early radio detectors. Developments in quantum physics led to work on the movement of the transistor in 1947,^[3] the integrated circuit in 1958, and the MOSFET (metal-oxide semiconductor field-effect transistor) in 1959.

Materials

Most silicon ICs are constructed from silicon.

Silicon crystals are the most common semiconductor materials used in microelectronics and photonics.

A large number of elements and compounds have semiconductor properties, including [12]

- Certain pure elements are found in group 14 of the periodic table. The most commercially important of these elements are silicon and germanium. Tellurium and selenium are used less effectively because they have 4 valence electrons in their outermost shell, which gives them the ability to gain or lose electrons equally in the same way.
- Binary compounds, particularly between elements in groups 13 and 15, such as gallium, arsenic, groups 11 and 16, groups 14 and 16, and between different group 14 elements, e.g. silicon carbide.
- Certain binary compounds, oxides, and alloys.
- Organic semiconductor, such as organic compounds.
- Semiconductor metal-organic frameworks (MOFs)

The most common semiconductor materials are crystalline solids, but amorphous and liquid semiconductors are also known. These include hydrogenated amorphous silicon and solutions of silicon, selenium, and tellurium in a variety of proportions. These compounds share with known semiconductors the properties of immediate conductivity and a rapid variation of conductivity with temperature, as well as occasional optical properties. Such disordered materials lack the tight crystalline structure of conventional semiconductors such as silicon. They have generally used in thin-film structures, which do not require material of higher electronic quality, being relatively insensitive to impurities and radiation damage.

Preparation of semiconductor materials

Almost all of today's electronic technology involves the use of semiconductors, with the most important ones being the integrated circuit (IC), which are found in desktop, laptop, wireless, cell phones, and other electronic devices. Semiconductors for ICs are manufactured by using an ideal semiconductor material, chemical purity is paramount. Any small impurities can have a drastic effect on how the semiconductor material behaves due to the scale at which the materials are used [13].

A high degree of crystalline perfection is also required. Many faults in the crystal structure (such as dislocations, voids, and grain boundaries) interfere with the semiconductor properties of the material. Crystalline faults are a major cause of defective semiconductor devices. The larger the crystal, the more difficult it is to achieve the necessary perfection. Current mass production processes for crystal begin between 100 and 300 mm (3.9 and 11.8 in) in diameter, grown as cylinders and sliced into wafers.

There is a continuous effort to develop new ways to prepare semiconductor materials for ICs. One process is called *thermal oxidation*, which forms silicon dioxide on the surface of the silicon. This is used as a gate insulator and field oxide. Other processes are called *photolithography* and *photocopying*. This process is what creates the patterns on the silicon in the integrated circuit.

Ultraviolet light is used along with a *photomask* beam to create a chemical change that generates the pattern for the circuit (2).

The next step is the *etch process* that is required. The part of the silicon that was not covered by the photomask beam from the previous step can now be etched. The etch process typically uses either a liquid or gaseous etchant. Plasma etching usually involves an *etch gas* (formed in a low-pressure chamber to create plasma). A common etch gas is *dichlorosilane*, or more commonly known as *silane*. A high accelerating voltage between the cathode and anode is what creates the plasma in the chamber. The *silane* reacts to form the etchant, which causes it to be hit by the positively charged ions that are released from the plasma. The result is silicon that is etched *anisotropically* (3).

The last process is called *doping*. This is the process that gives the semi-conducting material its desired semi-conducting properties. It is also known as *diffusing*. The process introduces an impurity atom to the system, which causes the *p-n junction*. To get the impurity atoms embedded in the silicon wafer, the wafer is first put in a 1,100 degree Celsius chamber. The atoms are injected as well as randomly diffuse with the silicon. After the process is completed and the silicon has reached room temperature, the doping process is done and the semi-conducting material is ready to be used as an integrated circuit (4).



BZX84C0V3 THRU BZX84C33

250mW ZENER DIODE
3.3 VOLTS THRU 33 VOLTS
5% TOLERANCE



SOT-23 CASE

ABSOLUTE MAXIMUM RATINGS
Power Dissipation (at $T_A = 25^{\circ}\text{C}$)
Operating and Storage Temperature
Thermal Resistance

SYMBOLS
 P_D
 T_J, T_{stg}
 $R_{\theta JA}$

250
-55 to +125
257

UNIT
mW
 $^{\circ}\text{C}$
 $^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}\text{C}$, $I_Z = 2.0\text{mA}$ UNLESS OTHERWISE SPECIFIED)

Part No.	Zener Voltage V_Z (V)	Test Current I_Z (mA)	Maximum Zener Impedance		Minimum Zener Current		Maximum Zener Current	Maximum Operating Temperature Coefficient	Working Case
			Z_{0V10}	Z_{0V5}	I_{Z0V10}	I_{Z0V5}			
			Ω	Ω	μA	μA		%/C	
BZX84C03	3.0	5.0	25	20	1.0	0.5	25	±10	35
BZX84C04	3.3	5.0	25	20	1.0	0.5	25	±10	35
BZX84C05	3.6	5.0	25	20	1.0	0.5	25	±10	35
BZX84C06	3.9	5.0	25	20	1.0	0.5	25	±10	35
BZX84C07	4.2	5.0	25	20	1.0	0.5	25	±10	35
BZX84C08	4.5	5.0	25	20	1.0	0.5	25	±10	35
BZX84C09	4.8	5.0	25	20	1.0	0.5	25	±10	35
BZX84C10	5.1	5.0	25	20	1.0	0.5	25	±10	35
BZX84C11	5.4	5.0	25	20	1.0	0.5	25	±10	35
BZX84C12	5.7	5.0	25	20	1.0	0.5	25	±10	35
BZX84C13	6.0	5.0	25	20	1.0	0.5	25	±10	35
BZX84C14	6.3	5.0	25	20	1.0	0.5	25	±10	35
BZX84C15	6.6	5.0	25	20	1.0	0.5	25	±10	35
BZX84C16	6.9	5.0	25	20	1.0	0.5	25	±10	35
BZX84C17	7.2	5.0	25	20	1.0	0.5	25	±10	35
BZX84C18	7.5	5.0	25	20	1.0	0.5	25	±10	35
BZX84C19	7.8	5.0	25	20	1.0	0.5	25	±10	35
BZX84C20	8.1	5.0	25	20	1.0	0.5	25	±10	35
BZX84C21	8.4	5.0	25	20	1.0	0.5	25	±10	35
BZX84C22	8.7	5.0	25	20	1.0	0.5	25	±10	35
BZX84C23	9.0	5.0	25	20	1.0	0.5	25	±10	35
BZX84C24	9.3	5.0	25	20	1.0	0.5	25	±10	35
BZX84C25	9.6	5.0	25	20	1.0	0.5	25	±10	35
BZX84C26	9.9	5.0	25	20	1.0	0.5	25	±10	35
BZX84C27	10.2	5.0	25	20	1.0	0.5	25	±10	35
BZX84C28	10.5	5.0	25	20	1.0	0.5	25	±10	35
BZX84C29	10.8	5.0	25	20	1.0	0.5	25	±10	35
BZX84C30	11.1	5.0	25	20	1.0	0.5	25	±10	35
BZX84C31	11.4	5.0	25	20	1.0	0.5	25	±10	35
BZX84C32	11.7	5.0	25	20	1.0	0.5	25	±10	35
BZX84C33	12.0	5.0	25	20	1.0	0.5	25	±10	35

Central
Semiconductor Corp.

DESCRIPTION

The CENTRAL SEMICONDUCTOR BZX84C0V3 Series Silicon Zener Diode is a high quality voltage regulator for use in industrial, commercial, entertainment and computer applications.

Properties Of a Semi Conductor

Variable electrical conductivity

Semiconductors in their natural state are poor conductors because a *valence* restricts the flow of electrons, and semiconductors have their valence bands filled, preventing the entire flow of new electrons. Special doped techniques allow semiconducting materials to behave like conducting materials, such as *doping* or *gating*. These modifications have two categories: *n-type* and *p-type*. These refer to the excess or shortage of electrons, respectively. A balanced number of electrons would cause a current to flow throughout the material.[1]

Heterojunctions

Heterojunctions occur when two differently doped semiconducting materials are joined. For example, a configuration could consist of *p-doped* and *n-doped* germanium. This results in an exchange of electrons and holes between the differently doped semiconducting materials. The *n-doped* germanium would have an excess of electrons, and the *p-doped* germanium would have an excess of holes. The transfer occurs until an equilibrium is reached by a process called *diffusion*, which causes the migrating electrons from the *n-type* to come in contact with the migrating holes from the *p-type*. The result of this process is a narrow strip of immobile ions, which causes an electric field across the junction.[1][2]

Excited electrons

A difference in electric potential on a semiconducting material would cause it to leave thermal equilibrium and create a non-equilibrium situation. This involves electrons and holes at the system, which occurs via a process called *photoconductive effect*. Whenever thermal equilibrium is disturbed on a semiconducting material, the number of holes and electrons changes. Such disruptions can occur as a result of a temperature difference or *gating*, which can raise the system and create electrons and holes. The process that creates and stabilizes electrons and holes are called *generation* and *recombination*, respectively.[1]

Light emission

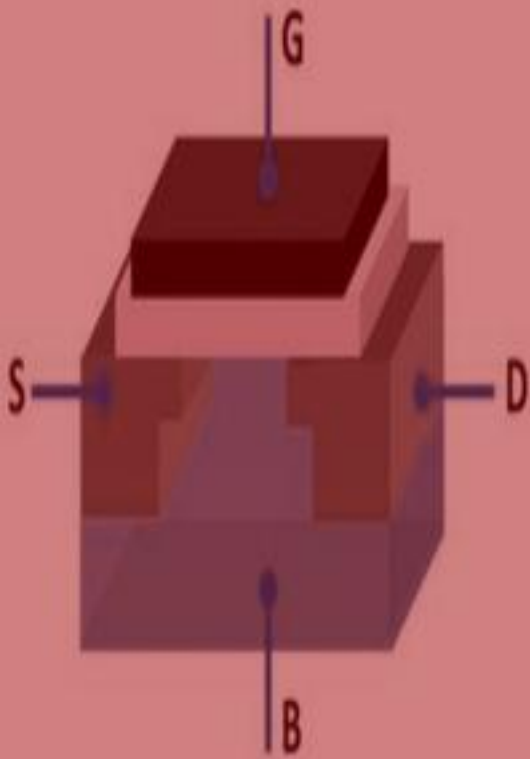
In certain semiconductors, excited electrons can return by emitting light instead of producing heat. [2] These semiconductors are used in the construction of *light emitting diodes* and *transistors* (quantum dots).

High thermal conductivity

Semiconductors with high thermal conductivity can be used for heat dissipation and improving thermal management of electronics.

Thermal energy conversion

Semiconductors have large **thermoelectric** **power factors** making them useful in **thermoelectric generators**, as well as high **thermoelastic** figures of merit making them useful in **thermoelectric coolers**. [3]



What is a Semiconductor?

A **semiconductor** material has an electrical conductivity value falling between that of a conductor, such as metallic copper, and an insulator, such as glass. Its conductivity falls in its intermediate class, usually between the square root to its **conducting** properties may be altered in useful ways by introducing impurities ("doping") into its crystal structure. When two differently doped regions join in the same crystal, a semiconductor junction is created. The behavior of charge carriers, which include electrons, ions, and electron holes, at these junctions is the basis of diodes, transistors, and many modern electronic devices. Some examples of semiconductors are silicon, germanium, gallium arsenide, and elements near the so-called "metalloid staircase" on the periodic table. When silicon, gallium arsenide is the second-most common semiconductor and is used in most diodes, solar cells, microwave-frequency integrated circuits, and others. Silicon is a critical element for fabricating most electronic circuits.

Semiconductor devices can display a range of useful properties, such as allowing current to flow more easily in one direction than the other, allowing variable resistance, and having sensitivity to light or heat. Because the electrical properties of a semiconductor material can be modified by doping, and by the application of electrical fields or light, devices made from semiconductors can be used for amplification, switching, and energy conversion.

The conductivity of silicon is increased by adding a small amount (of the order of 1 in 10⁷) of pentavalent elements, phosphorus, or arsenic, or trivalent elements boron, gallium, indium or zinc. This process is known as doping, and the resulting semiconductors are known as doped or extrinsic semiconductors. Apart from doping, the conductivity of a semiconductor can be improved by increasing its temperature. This is contrary to the behavior of a metal, in which conductivity decreases with an increase in temperature.

The modern understanding of the properties of a semiconductor relies on quantum physics to explain the movement of charge carriers in a crystal lattice.[1] Doping greatly increases the number of charge carriers within the crystal. When a doped semiconductor contains free holes, it is called "p-type", and when it contains free electrons, it is known as "n-type". The semiconductor elements used in electronic devices are doped under precise conditions to control the concentrations and regions of p- and n-type regions. A single semiconductor device crystal can have many p- and n-type regions; the p-n junctions between these regions are responsible for the useful electronic behavior. Using a laser-point probe, one can determine quickly whether a semiconductor sample is p or n-type.[2]

Some of the properties of semiconductor materials were observed throughout the mid 19th and first decades of the 20th century. The first practical application of semiconductors in electronics, was the 1964 development of the radio-shield detector, a p-n junction diode used in early radio detectors. Developments in quantum physics led to work on the movement of the transistor in 1947,[3] the integrated circuit in 1958, and the MOSFET (metal-oxide semiconductor field-effect transistor) in 1959.

Materials

Most silicon ICs are constructed from silicon.

Silicon crystals are the most common semiconductor materials used in microelectronics and photonics.

A large number of elements and compounds have semiconductor properties, including [12]

- Certain pure elements are found in group 14 of the periodic table. The most commercially important of these elements are silicon and germanium. Tellurium and selenium are used less effectively because they have 4 valence electrons in their outermost shell, which gives them the ability to gain or lose electrons equally in the same way.
- Binary compounds, particularly between elements in groups 12 and 16, such as gallium, arsenic, groups 13 and 16, groups 14 and 16, and between different group 14 elements, e.g. silicon carbide.
- Certain binary compounds, oxides, and alloys.
- Organic semiconductor, such as organic compounds.
- Semiconductor metal-organic frameworks (MOFs)

The most common semiconductor materials are crystalline solids, but amorphous and liquid semiconductors are also known. These include hydrogenated amorphous silicon and solutions of silicon, selenium, and tellurium in a variety of proportions. These compounds share with known semiconductors the properties of immediate conductivity and a rapid variation of conductivity with temperature, as well as occasional optical properties. Such disordered materials lack the tight crystalline structure of conventional semiconductors such as silicon. They have generally used in thin-film structures, which do not require material of higher electronic quality, being relatively insensitive to impurities and radiation damage.

Preparation of semiconductor materials

Almost all of today's electronic technology involves the use of semiconductors, with the most important ones being the integrated circuit (IC), which are found in desktop, laptop, wireless, cell phones, and other electronic devices. Semiconductors for ICs are manufactured by using an ideal semiconductor material, chemical purity is paramount. Any small imperfections can have a drastic effect on how the semiconductor behaves due to the scale at which the materials are used [13].

A high degree of crystalline perfection is also required. Many faults in the crystal structure (such as dislocations, voids, and grain boundaries) interfere with the semiconductor properties of the material. Crystalline faults are a major cause of defective semiconductor devices. The larger the crystal, the more difficult it is to achieve the necessary perfection. Current mass production processes for crystal begin between 100 and 300 mm (3.9 and 11.8 in) in diameter, grown as cylinders and sliced into wafers.

There is a continuous effort to develop new ways to prepare semiconductor materials for ICs. One process is called *thermal oxidation*, which forms silicon dioxide on the surface of the silicon. This is used as a gate insulator and field oxide. Other processes are called *photolithography* and *photocopying*. This process is what creates the patterns on the silicon in the integrated circuit.

Ultraviolet light is used along with a photoresist layer to create a chemical change that generates the pattern for the circuit (2).

The next step is the *etch process* that is required. The part of the silicon that was not covered by the photoresist layer from the previous step can now be etched. The etch process typically uses either a liquid or gaseous etchant. Plasma etching usually involves an *etch gas* (formed in a low-pressure chamber to create plasma). A common *etch gas* is *dichlorosilane*, or more commonly known as *silane*. A high accelerating voltage between the cathode and anode is what creates the plasma in the chamber. The *silane* reacts to form the etchant, which causes it to be hit by the positively charged ions that are released from the previous. The result is silicon that is etched *anisotropically* (3).

The last process is called *doping*. This is the process that gives the semi-conducting material its desired semi-conducting properties. It is also known as *diffusing*. The process introduces an impurity atom to the system, which causes the *p-n junction*. To get the impurity atoms embedded in the silicon wafer, the wafer is first put in a 1,000 degree Celsius chamber. The atoms are injected as well as randomly diffuse with the silicon. After the process is completed and the silicon has reached room temperature, the doping process is done and the semi-conducting material is ready to be used as an integrated circuit (4).

